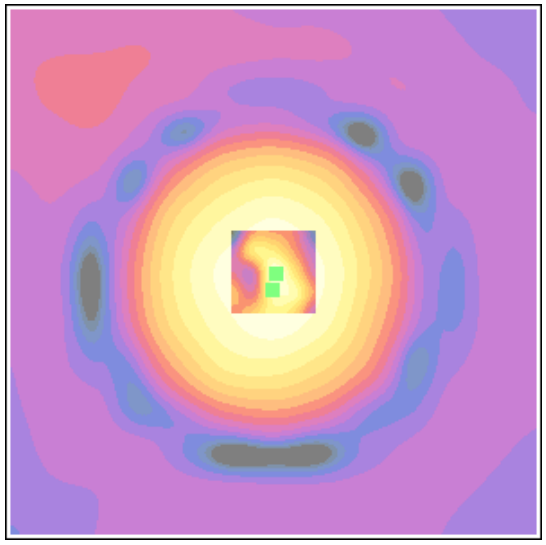
CELL BC-0

Test Laboratory: COMPTEST/KYOCERA Date: 02/21/2013

FCC_S2150_TCoil_CELL-BC0_Ch.1013 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.6 dB
ABM1 comp = -0.485 dB A/m
BWC Factor = 0.15103 dB
Location: 0, 1.7, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.3 dB
ABM1 comp = -0.117 dB A/m
BWC Factor = 0.15103 dB
Location: -0.2, 0.2, 3.7 mm



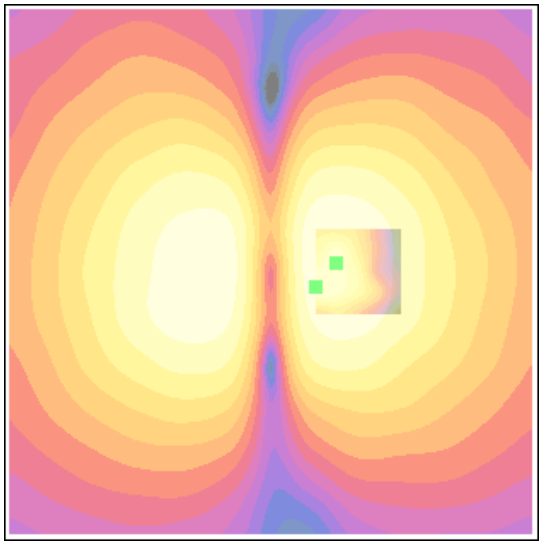
0 dB = 426.9

Test Laboratory: COMPTEST/KYOCERA Date: 02/21/2013

FCC_ S2150_TCoil_CELL-BC0 _Ch. 1013 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.8 dB
ABM1 comp = -8.19 dB A/m
BWC Factor = 0.15103 dB
Location: -6.2, -0.8, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.1 dB
ABM1 comp = -7.95 dB A/m
BWC Factor = 0.15103 dB
Location: -4.3, 1.4, 3.7 mm



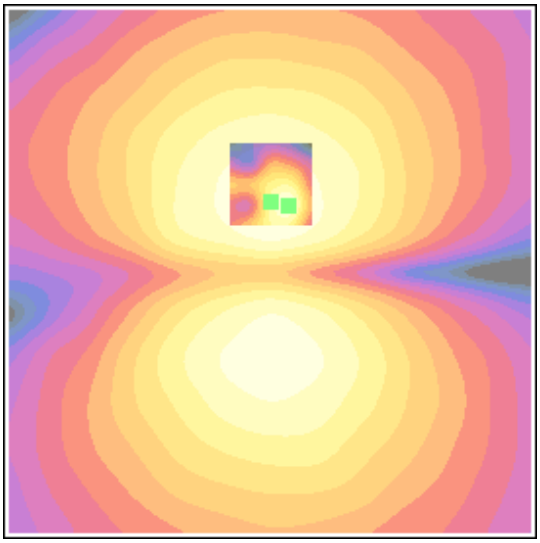
0 dB = 308.7

Test Laboratory: COMPTEST/KYOCERA Date: 02/21/2013

FCC_ S2150_TCoil_CELL-BC0 _Ch. 1013 y (transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.8 dB
ABM1 comp = -7.86 dB A/m
BWC Factor = 0.15103 dB
Location: 0, -6.7, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.3 dB
ABM1 comp = -8.39 dB A/m
BWC Factor = 0.15103 dB
Location: -1.6, -6.3, 3.7 mm



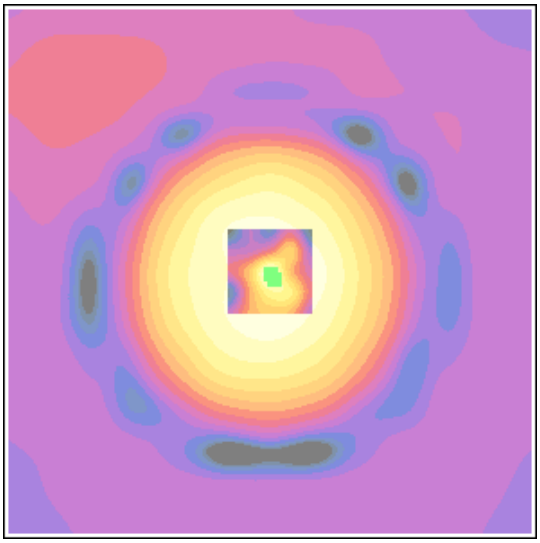
0 dB = 308.2

Test Laboratory: COMPTEST/KYOCERA Date: 02/21/2013

FCC_ S2150_TCoil_CELL-BC0_Ch.384 z (axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.0 dB
ABM1 comp = -0.684 dB A/m
BWC Factor = 0.15103 dB
Location: -0.4, 0.8, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.8 dB
ABM1 comp = 0.007 dB A/m
BWC Factor = 0.15103 dB
Location: 0, 0.2, 3.7 mm



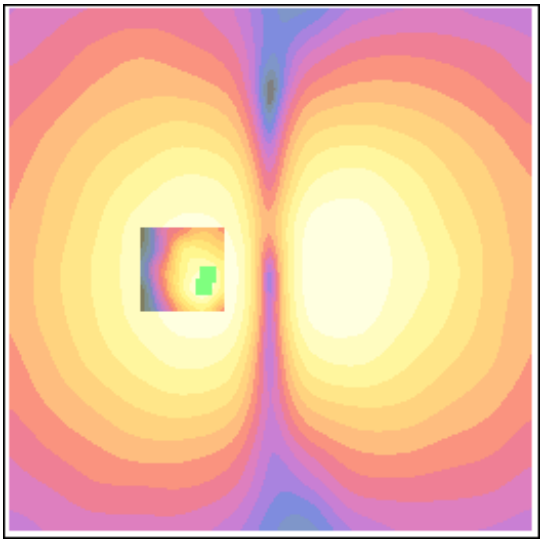
0 dB = 397.2

Test Laboratory: COMPTEST/KYOCERA Date: 02/21/2013

FCC_ S2150_TCoil_CELL-BC0 _Ch.384 x (longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.3 dB
ABM1 comp = -7.84 dB A/m
BWC Factor = 0.15103 dB
Location: 5.8, 0.4, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.1 dB
ABM1 comp = -7.61 dB A/m
BWC Factor = 0.15103 dB
Location: 6.3, 1.6, 3.7 mm



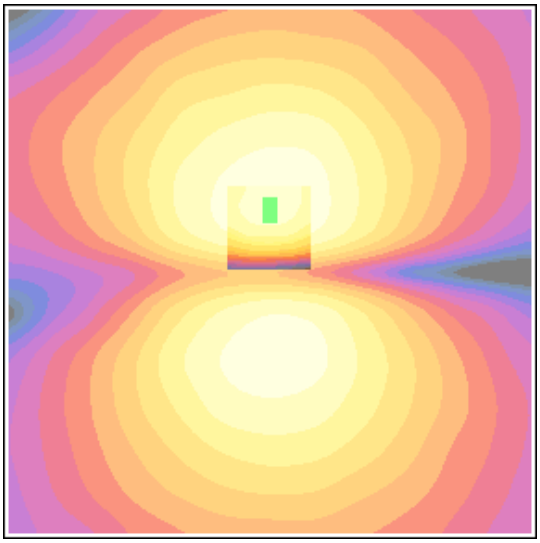
0 dB = 326.3

Test Laboratory: COMPTEST/KYOCERA Date: 02/21/2013

FCC_ S2150_TCoil_CELL-BC0 _Ch.384 y(transversal)
Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.7 dB
ABM1 comp = -7.91 dB A/m
BWC Factor = 0.15103 dB
Location: 0, -5.4, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.15103 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.8 dB
ABM1 comp = -7.64 dB A/m
BWC Factor = 0.15103 dB
Location: 0, -6.4, 3.7 mm



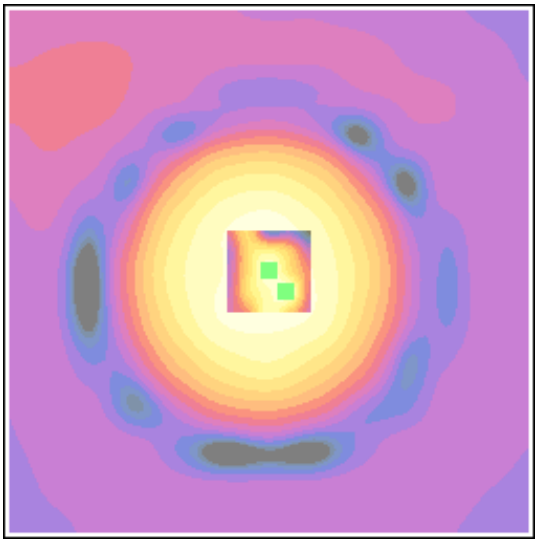
0 dB = 304.3

Test Laboratory: COMPTEST/KYOCERA Date: 02/21/2013

FCC_ S2150_TCoil_CELL-BC0_Ch. 777 z(axial)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.9 dB
ABM1 comp = -0.191 dB A/m
BWC Factor = 0.151969 dB
Location: 0, 0, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.0 dB
ABM1 comp = -1.39 dB A/m
BWC Factor = 0.151969 dB
Location: -1.6, 2, 3.7 mm

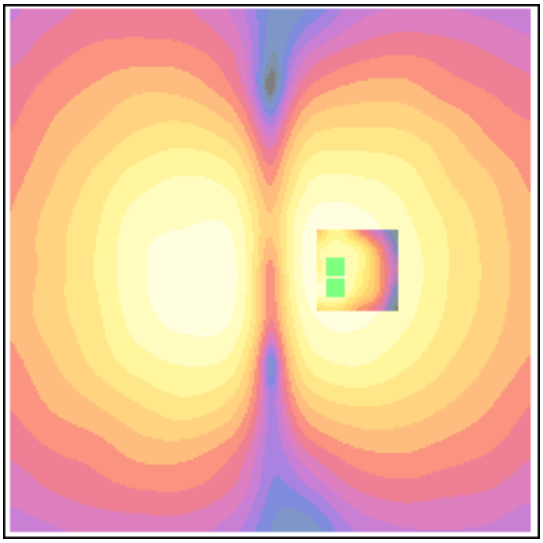


0 dB = 393.4

FCC_ S2150_TCoil_CELL- BC0_Ch. 777 x(longitudinal)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.0 dB
ABM1 comp = -7.93 dB A/m
BWC Factor = 0.151969 dB
Location: -6.2, -0.4, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.9 dB
ABM1 comp = -8.01 dB A/m
BWC Factor = 0.151969 dB
Location: -6.1, 1.6, 3.7 mm



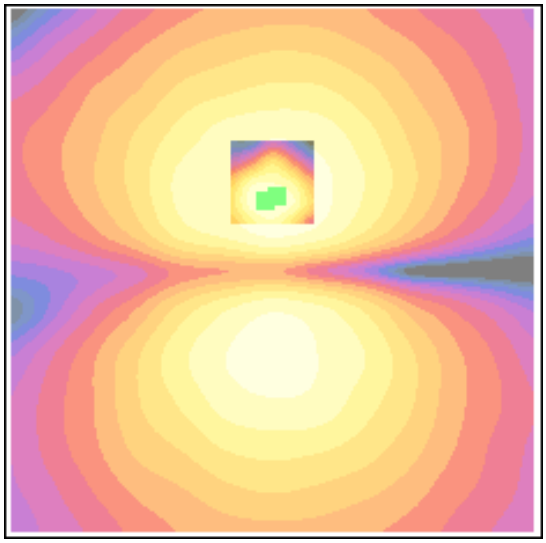
0 dB = 317.4

Test Laboratory: COMPTEST/KYOCERA Date: 02/21/2013

FCC_ S2150_TCoil_CELL- BC0_Ch. 777 y(transveral)
Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.6 dB
ABM1 comp = -8.14 dB A/m
BWC Factor = 0.151969 dB
Location: -0.4, -7.1, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -8.43 dB A/m
BWC Factor = 0.151969 dB
Location: 0.8, -6.5, 3.7 mm



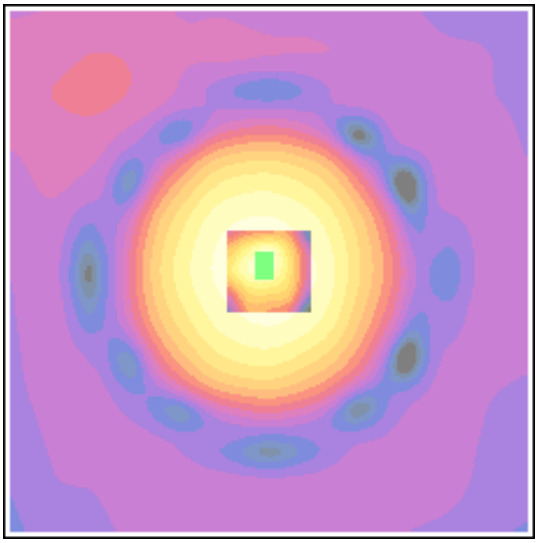
0 dB = 300.4

PCS

FCC_ S2150_TCoil_PCS_Ch. 25 z(axial)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.2 dB
ABM1 comp = 0.255 dB A/m
BWC Factor = 0.151969 dB
Location: 0.4, 0, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 53.5 dB
ABM1 comp = 0.304 dB A/m
BWC Factor = 0.151969 dB
Location: 0.4, -1, 3.7 mm



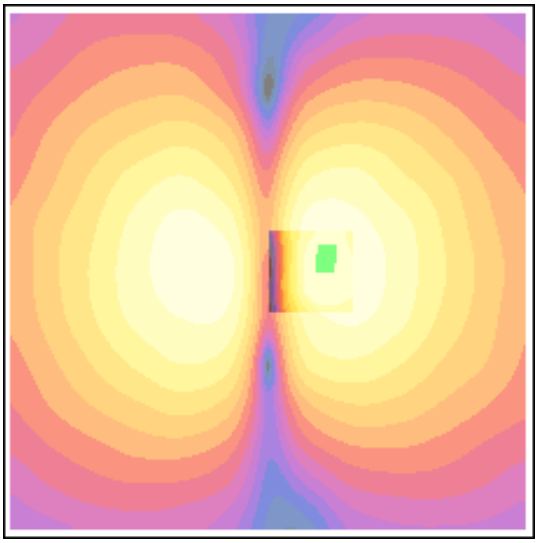
0 dB = 459.7

Test Laboratory: COMPTEST/KYOCERA Date: 02/20/2013

FCC_ S2150_TCoil_PCS_ Ch. 25 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.2 dB
ABM1 comp = -7.70 dB A/m
BWC Factor = 0.151969 dB
Location: -5.4, -0.8, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.0 dB
ABM1 comp = -7.97 dB A/m
BWC Factor = 0.151969 dB
Location: -5.8, -1.8, 3.7 mm



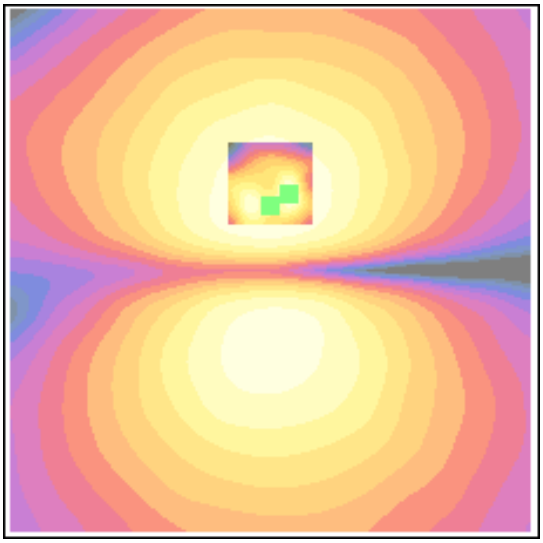
0 dB = 324.6

Test Laboratory: COMPTEST/KYOCERA Date: 02/20/2013

FCC_ S2150_TCoil_PCS_ Ch. 25 y(transversal)
Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.8 dB
ABM1 comp = -7.67 dB A/m
BWC Factor = 0.151969 dB
Location: 0, -6.3, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.2 dB
ABM1 comp = -8.42 dB A/m
BWC Factor = 0.151969 dB
Location: -1.8, -7.3, 3.7 mm

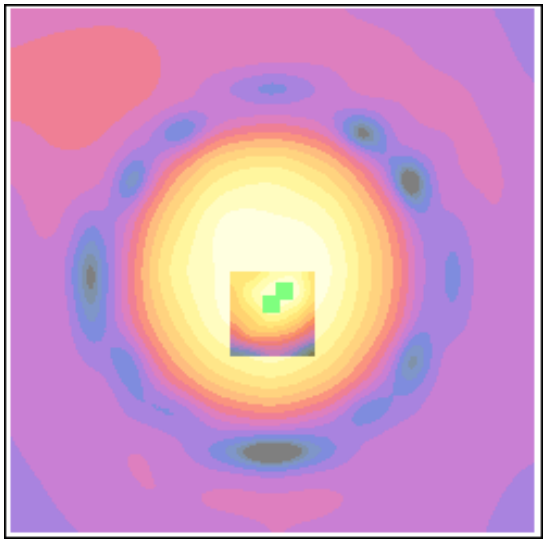


0 dB = 308.6

FCC_ S2150_TCoil_PCS Ch. 600 z(axial)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.7 dB
ABM1 comp = -1.35 dB A/m
BWC Factor = 0.151969 dB
Location: 0, 3.3, 3.7 mm

General Scans_600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.6 dB
ABM1 comp = -0.730 dB A/m
BWC Factor = 0.151969 dB
Location: -1.2, 2, 3.7 mm



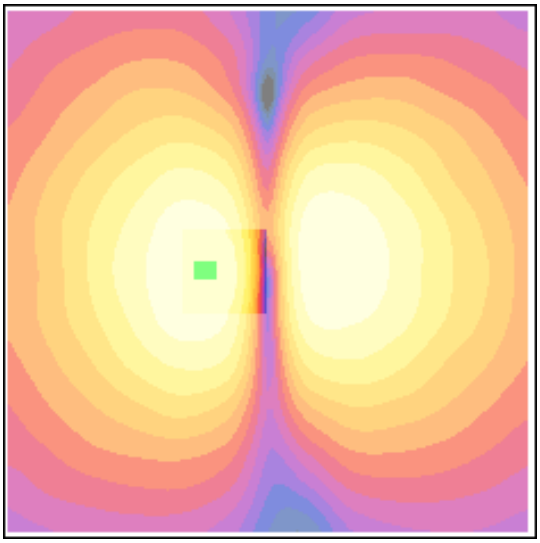
0 dB = 385.7

Test Laboratory: COMPTEST/KYOCERA Date: 02/20/2013

FCC_ S2150_TCoil_PCS Ch. 600 x (longitudinal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.1 dB
ABM1 comp = -7.87 dB A/m
BWC Factor = 0.151969 dB
Location: 5.8, 0, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.0 dB
ABM1 comp = -7.85 dB A/m
BWC Factor = 0.151969 dB
Location: 6.2, 0, 3.7 mm



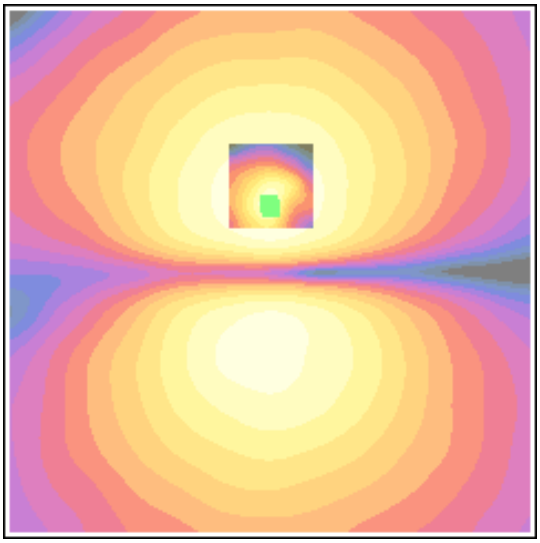
0 dB = 319.3

Test Laboratory: COMPTEST/KYOCERA Date: 02/20/2013

FCC_ S2150_TCoil_PCS_ Ch. 600 y(transversal)
Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.1 dB
ABM1 comp = -7.52 dB A/m
BWC Factor = 0.151969 dB
Location: 0, -6.3, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.0 dB
ABM1 comp = -7.53 dB A/m
BWC Factor = 0.151969 dB
Location: 0.2, -6.5, 3.7 mm

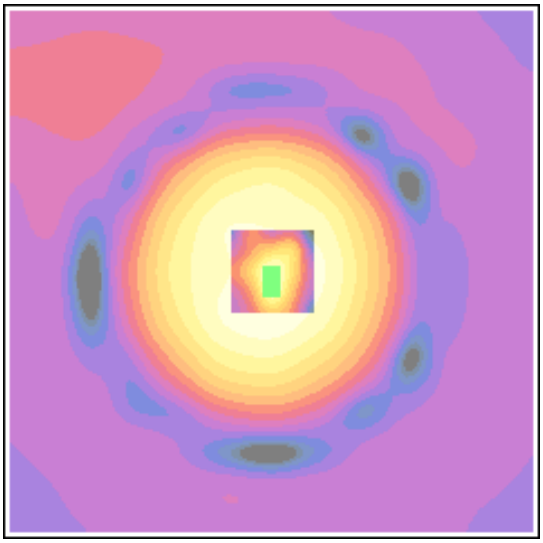


0 dB = 320.6

FCC_ S2150_TCoil_PCS_ Ch.1175 z(axial)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 51.9 dB
ABM1 comp = -0.696 dB A/m
BWC Factor = 0.151969 dB
Location: 0, 1.7, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 52.9 dB
ABM1 comp = -0.052 dB A/m
BWC Factor = 0.151969 dB
Location: 0, 0.4, 3.7 mm



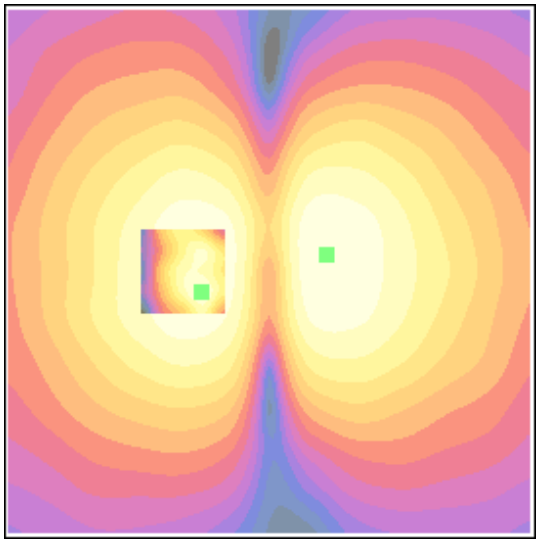
0 dB = 393.4

Test Laboratory: COMPTEST/KYOCERA Date: 02/20/2013

FCC_ S2150_TCoil_PCS _Ch. 1175 x(longitudinal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 50.0 dB
ABM1 comp = -7.76 dB A/m
BWC Factor = 0.151969 dB
Location: -5.4, -1.7, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.7 dB
ABM1 comp = -8.11 dB A/m
BWC Factor = 0.151969 dB
Location: 6.5, 2, 3.7 mm



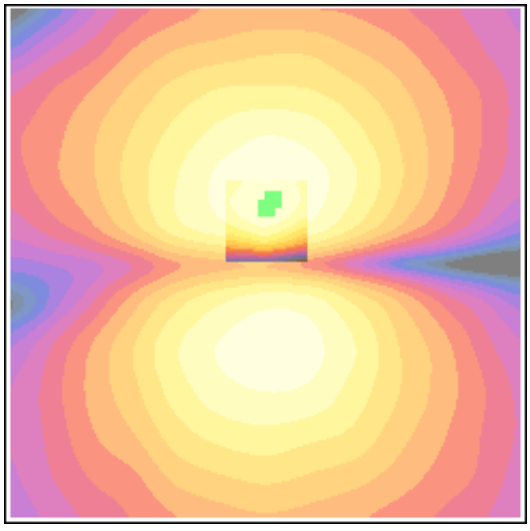
0 dB = 316.1

Test Laboratory: COMPTEST/KYOCERA Date: 02/20/2013

FCC_ S2150_TCoil_PCS_ Ch. 1175 y(transversal)
Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1
Medium: T-Coil,Medium parameters used: σ = 0 mho/m, ε_r = 1; ρ = 0 kg/m^3
Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section
DASY4 Configuration:
Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011
Sensor-Surface: 0mm (Fix Surface),
Electronics: DAE4 Sn527,Calibrated: 7/30/2012
Measurement SW: DASY4, V4.7 Build 80
Postprocessing SW: SEMCAD, V1.8 Build 186
Temperature: Room T = 21.8 □□□ 1 deg C, Liquid T = 22.0 □□□ 1 deg C

General Scans_1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.5 dB
ABM1 comp = -7.94 dB A/m
BWC Factor = 0.151969 dB
Location: 0, -5.4, 3.7 mm

General Scans_1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):
Measurement grid: dx=10mm, dy=10mm
Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav
BWC applied: 0.151969 dB
Device Reference Point: 0.000, 0.000, -6.30 mm
Cursor:
ABM1/ABM2 = 49.4 dB
ABM1 comp = -8.16 dB A/m
BWC Factor = 0.151969 dB
Location: -0.6, -6.4, 3.7 mm



0 dB = 299.4